

<b>PATENT ASSIGNMENT COVER SHEET</b>
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Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT6363464

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
SABASTIAN K GEORGE	08/06/2020
MOHAN CHIRUVOLU	03/14/2019
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	MEDTRONIC ENGINEERING AND INNOVATION CENTER PRIVATE LIMITED
<b>Street Address:</b>	DLF CYBER CITY, BLOCK NO. 3, GROUND FLOOR
<b>Internal Address:</b>	PLOT NO. 129 TO 132, APHB COLONY
<b>City:</b>	GACHIBOWLI, HYDERABAD
<b>State/Country:</b>	INDIA
<b>Postal Code:</b>	500019
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16789746
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(203)492-5785
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	2034925000
<b>Email:</b>	rs.patents.two@medtronic.com, dspinillo@carterdeluca.com, docket@carterdeluca.com
<b>Correspondent Name:</b>	COVIDIEN LP
<b>Address Line 1:</b>	60 MIDDLETOWN AVENUE
<b>Address Line 2:</b>	MAILSTOP 54, LEGAL DEPT
<b>Address Line 4:</b>	NORTH HAVEN, CONNECTICUT 06473
<b>ATTORNEY DOCKET NUMBER:</b>	A0000685US02 (203-12439)
<b>NAME OF SUBMITTER:</b>	BRADLEY SHELOWITZ
<b>SIGNATURE:</b>	/bradley shelowitz/
<b>DATE SIGNED:</b>	10/22/2020
<b>Total Attachments: 4</b> source=01713866#page1.tif	

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## DEED OF ASSIGNMENT

THIS DEED OF ASSIGNMENT IS EXECUTED BY

Sabastian Koduthully George, resident of Post Flat #303, Hemadurga Apartments, Jewel B, Road 2, PJR Layout, PJR Enclave Road, Chanda Nagar, Hyderabad, 500050, Inda (hereinafter "Assignor") (which expression unless repugnant to the meaning or context thereof shall mean and include their respective heirs and executors) of the **ONE PART**

IN FAVOUR OF

Medtronic Engineering and Innovation Center Private Limited  
Address: DLF Cyber City, Block No. 3, Ground Floor, Plot No. 129 to 132, APHB Colony, Gachibowli, Hyderabad 500019 India (hereinafter "Assignee") (which expression unless repugnant to the meaning or context thereof shall mean and include its successors and Assigns) and represented by its authorized signatory Mr/Ms. Divya Prakash Joshi, Director of the **OTHER PART**;

WHEREAS the Assignor is the inventor of an invention titled "TOOL ASSEMBLIES WITH A GAP LOCKING MEMBER", identified by reference number: A0000685US01 (203-12439), the subject of United States Provisional Patent Application Serial No. 62/817,807 filed March 13, 2019, hereinafter referred to as the "Invention".

Assignors hereby grant Assignee and Assignee's attorneys the power to insert the Serial No. and/or filing date of the above-described application(s) after such information becomes known to them.

WHEREAS Assignor is an employee of Assignee and recognizes that the Invention has been developed using the resources and facilities provided by Assignee in the course of the employment of Assignor, governed by the agreement of employment between Assignee and Assignor.

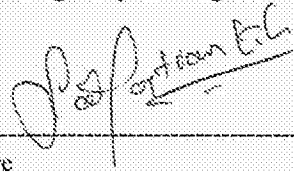
NOW THEREFORE, it is agreed that in consideration of the remuneration, facilities and perks received by Assignee, Assignor does hereby assign and transfer to Assignee the entire interest in the Invention disclosed in the invention disclosure with the above title and reference number, including all patent applications, utility model applications, design applications or other intellectual property rights, originating from the Invention, filed in any country including all divisional and continuation applications and the right to claim priority from such applications including the right to claim priority under the Paris Convention for the Protection of Industrial Property, all re-examination applications, all re-issue applications, and any patents, utility models, designs or other intellectual property rights which may issue for the Invention.

Assignor further agrees and warrants to execute all such further papers and perform such other acts as Assignee may reasonably request to obtain or maintain such patents, utility models, designs other intellectual property rights in any country.

It is understood and agreed to by the parties hereto, that on the execution of this Deed of Assignment, no rights of any nature whatsoever, in respect of such Intellectual Property, shall survive with Assignor. Assignor further undertakes not to

make any claim in the future with regard to such Intellectual Property assigned to the Assignee vide this Deed of Assignment.

Authorized signatory of Assignor



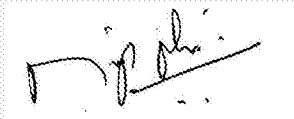
Signature

Name: Sebastian Koduthully George

Place, Date: BANGALORE, 06-AUG-2020

Assignee hereby acknowledges and agrees to such assignment and transfer

Authorized signatory of Assignee



Signature

Name: Divya Prakash Joshi

Place, Date: Hyderabad, August 06, 2020

## DEED OF ASSIGNMENT

THIS DEED OF ASSIGNMENT IS EXECUTED BY

Mohan Chiruvolu, resident of Post C 305, Vaishali Apts, St No.: 14, Lane No.: 3, Nagarjuna Nagar, Tarnaka, Secunderabad, 500017, India (hereinafter 'Assignor') (which expression unless repugnant to the meaning or context thereof shall mean and include their respective heirs and executors) of the **ONE PART**

IN FAVOUR OF

Medtronic Engineering and Innovation Center Private Limited  
Address: DLF Cyber City, Block No. 3, Ground Floor, Plot No. 129 to 132, APHB Colony, Gachibowli, Hyderabad 500019 India (hereinafter 'Assignee') (which expression unless repugnant to the meaning or context thereof shall mean and include its successors and Assigns) and represented by its authorized signatory Mr/Ms. Divya Prakash Joshi, Director of the **OTHER PART**;

WHEREAS the Assignor is the inventor of an invention titled "TOOL ASSEMBLIES WITH A GAP LOCKING MEMBER", identified by reference number: A0000685US01 (203-12439), the subject of United States Provisional Patent Application Serial No. 62/817,807 filed March 13, 2019, hereinafter referred to as the "Invention".

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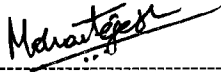
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Assignor further agrees and warrants to execute all such further papers and perform such other acts as Assignee may reasonably request to obtain or maintain such patents, utility models, designs other intellectual property rights in any country.

It is understood and agreed to by the parties hereto, that on the execution of this Deed of Assignment, no rights of any nature whatsoever, in respect of such Intellectual Property, shall survive with Assignor. Assignor further undertakes not to

make any claim in the future with regard to such Intellectual Property assigned to the Assignee vide this Deed of Assignment.

Authorized signatory of Assignor



Signature

Name: Mohan Chiruvolu

Place, Date: Hyderabad, 14-Mar-2019

Witness of Assignor:



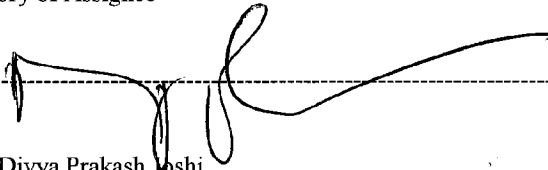
Signature

Name: P.M. SURESH KUMAR

Place, Date: Hyderabad, 14-Mar-2019

Assignee hereby acknowledges and agrees to such assignment and transfer

Authorized signatory of Assignee



Signature

Name: Divya Prakash Joshi

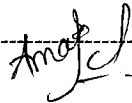
Place, Date: Hyderabad,

Divya Prakash Joshi  
Site Director  
Medtronic Engineering & Innovation Centre

Witness of Assignor:

Hyderabad, 29 Mar 19

Signature



Name: AMARSINH JADHAV

Place, Date: HYDERABAD - INDIA